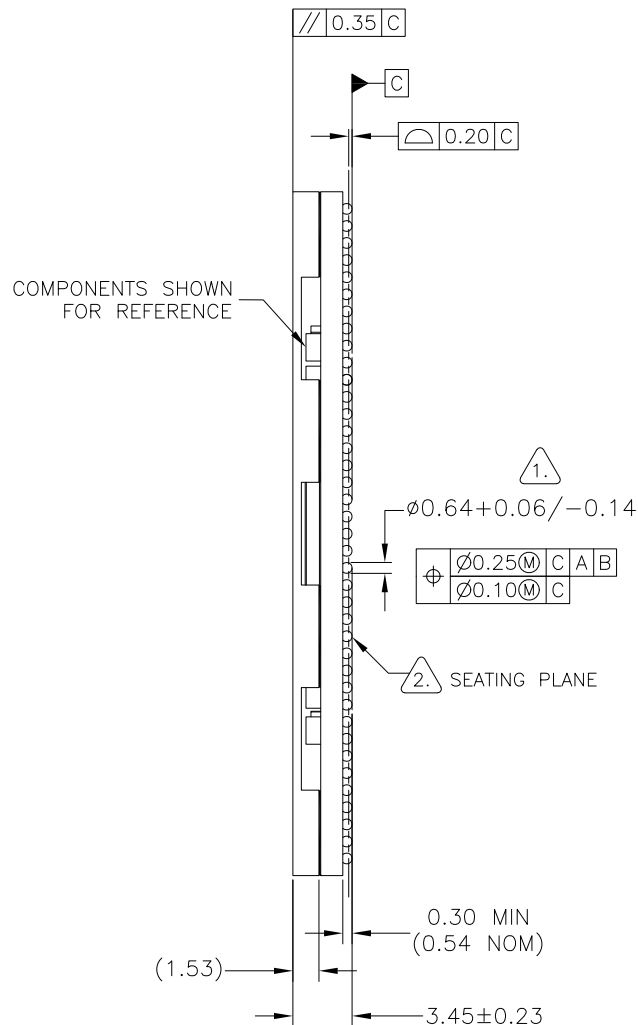


ECN NO.	REV.	DESCRIPTION OF CHANGE	EFFECTIVE DATE	ORIGINATOR
20250050	0	New release	03/05/2025	Erwin Q.
20250364	1	Updated package height with tolerance, added RTPFS460ZT-FC1509	09/23/2025	Tyler J.
20260061	2	Removed die outline in top view.	03/02/2026	Tyler J.



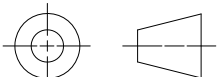
SIDE VIEW

BOTTOM VIEW

1509 Solder Balls

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-2009.

3. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

GENERAL TOLERANCE X.X ± 0.01 X.XX ± 0.05 X.XXX ± 0.03 ANGULAR ± 0.01° UNLESS OTHERWISE SPECIFIED INTERPRET DIM AND TOL PER ASME Y14.5M - 2009	PROJECTION 	 MICROCHIP Microchip Technology Inc., FPGA Business Unit 3850 N. 1st St. San Jose, CA 95134				
	APPROVALS	DATE	TITLE: RTPF500ZT-FC1509, RTPFS460ZT-FC1509 PACKAGE OUTLINE DWG			
	DRAWN Erwin Quiobo	03/05/2025	PKG. TYPE: 40.0 mm X 40.0 mm, 1.0 mm BALL PITCH, 1509 SOLDER BALLS, FLIP CHIP BGA			
	DIMENSIONS: Millimeters [inches] unless specified	CHECKED			MICROCHIP PART NUMBER: ---	MICROCHIP DWG. NUMBER: 1-14-12107
	ENG'R		SIZE B	VENDOR NAME: N/A	VENDOR PART NUMBER: ---	REV --
	RELEASED				SCALE: NONE	SHEET 1 OF 1

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